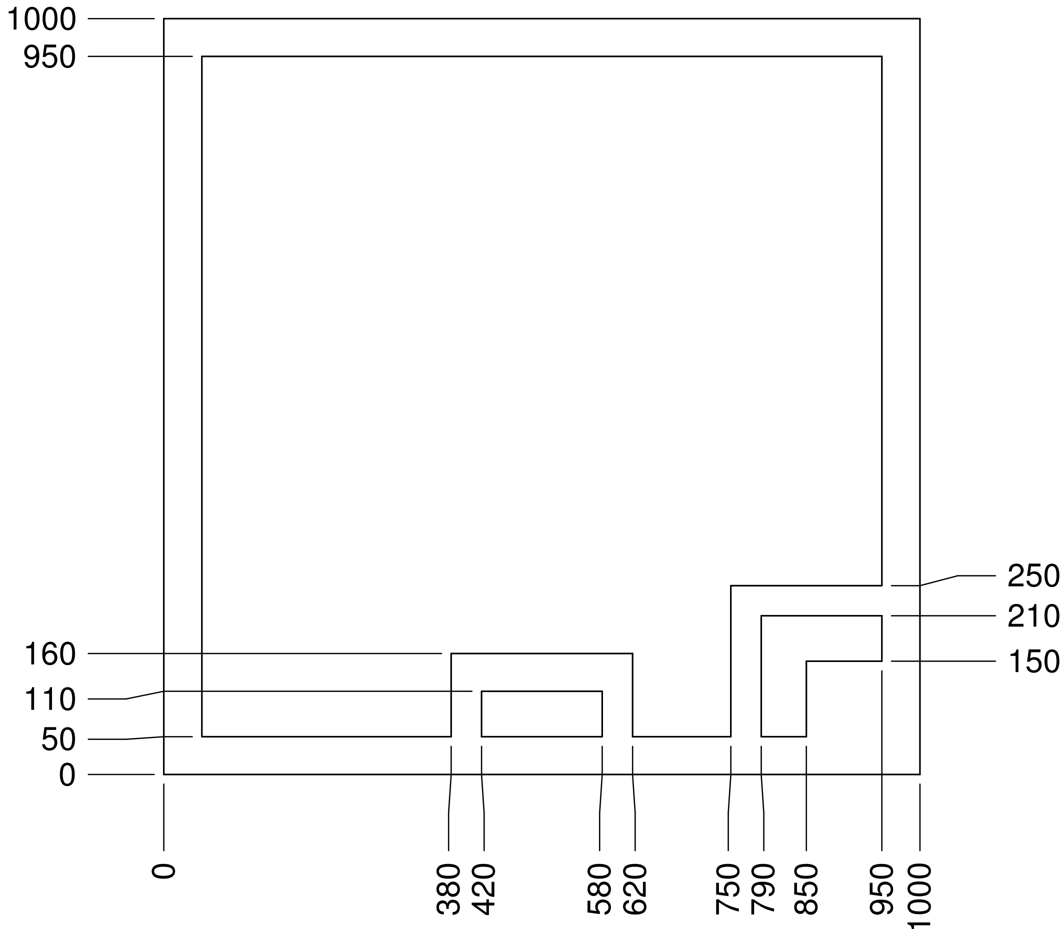
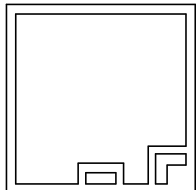
REVISIONS				
DATE	REV.	ECO	DESCRIPTION	APPROVED





SCALE 25:1

Notes: (Unless Otherwise Specified).

1) DIE MATERIAL IS SILICON.
2) DIE THICKNESS IS 250 um (10 MIL).
3) METALLIZATION 1.0 um ALUMINUM (Al) OVER 0.75 um SiO_2.
4) DIE IS WITHOUT PASSIVATION.
5) WIRE BONDABLE WITH GOLD (Au) OR ALUMINUM (Al) WIRE.
6) DIFFERENTIAL PAIR (2 PADS) WITH LARGE GROUND PAD.
7) RF / MICROWAVE PARASITIC TEST APPLICATIONS.
8) TOLERANCE = ±1 um.

DIMENSIONS IN MICRONS
1000 um = 1. 0mm

PART NUMBER SYSTEM						
TD	-	2	-	1.0	-	DIF
SILICON TEST DIE		BOND PADS		DIE SIZE (mm)		DIFFERENTIAL PAIR

TOLERANCE UNLESS NOTED	
X.XX	+/- 0.01
X.XXX	+/- 0.005
X.XXXX	+/- 0.0005
ANGLES	+/- 0.5°
ALL DIMENSIONS IN ☒ INCHES ☐ MILLIMETERS	
THIRD ANGLE PROJECTION	

APPROVALS		DATE
DRAWN	J. HINES	4/2/2010
ENG		
MFG		
QA		
CUST		
REVISED		

TopLine®

TITLE	Si TEST DIE TD SERIES		
SCALE 100:1	SIZE A	DRAWING NO. 151002	REV A
DO NOT SCALE DRAWING		SHEET 1 OF 1	